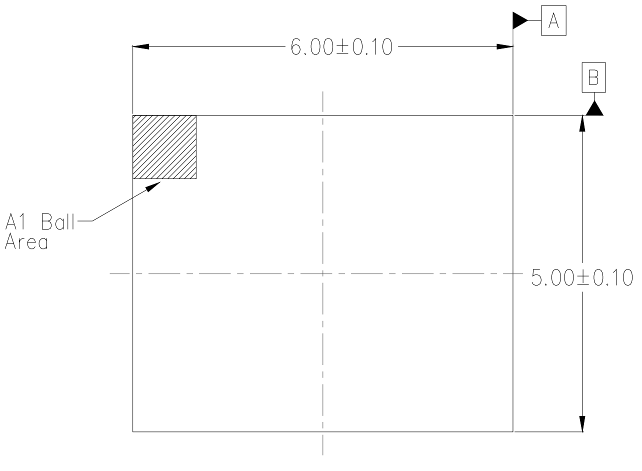
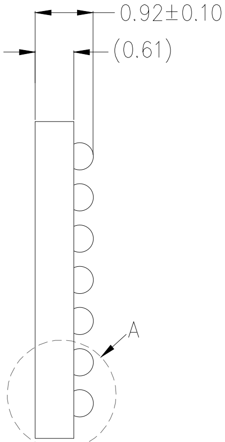
57- FCCSP, Package Outline Drawing

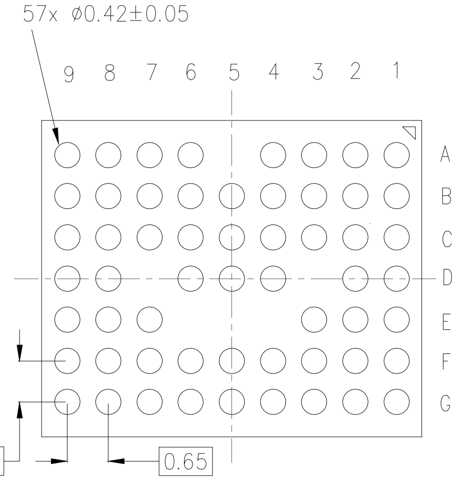
6.0x5.0x0.92 mm Body, 0.65 mm Pitch



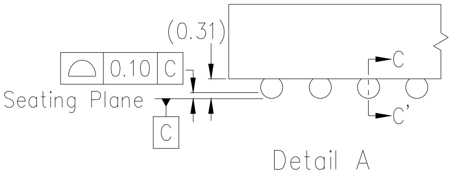
Top View



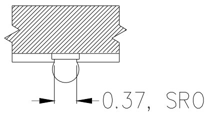
Side View



Bottom View



Detail A
(Rotated 90° CW)

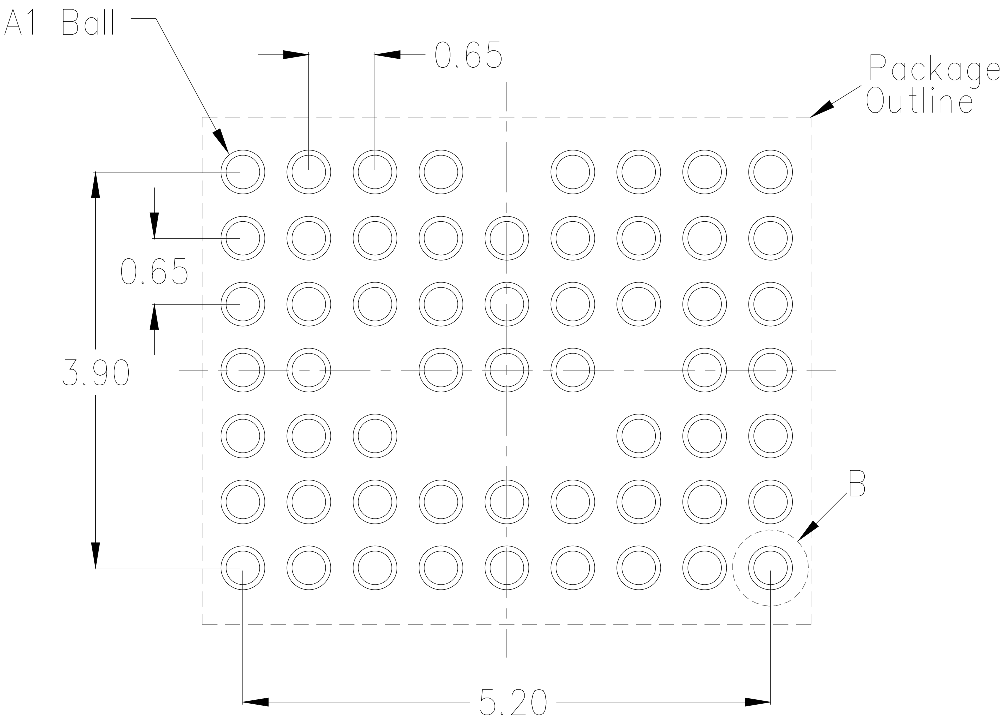


Section C–C'

57- FCCSP, Package Outline Drawing

6.0x5.0x0.92 mm Body, 0.65 mm Pitch

AVG57D1, PSC-4892-01, Rev00, Page 2



Recommended Land Pattern
(PCB Top View, NSMD Design)

Detail B

NOTES:

1. JEDEC compatible.
2. All dimensions are in mm and angles are in degrees.
3. Use ±0.05 mm tolerance for all other dimensions.
4. Numbers in ( ) are for references only.
5. Pre-reflow solderball diameter is ø0.4 mm.

Package Revision History

Date Created	Rev No.	Description
Oct 26, 2021	Rev 00	Initial Release